



FEATURES & BENEFITS

- Thermal Conductivity: 3 W/m·K
- Moderate Viscosity
- · Low Thermal Resistance
- High Thermal Conductivity
- Silicon-free
- Solvent-free





MAPPLICATIONS

- CPUs (Notebooks, PCs, Servers)
- LED Solid State Lighting
- GPUs

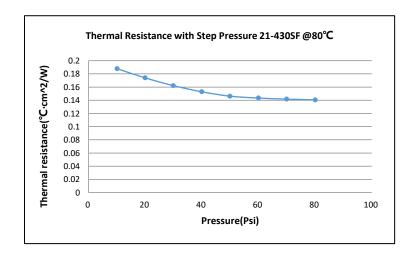
JONES Thermal Grease 21-430SF is a silicone-free based, high performance thermal interface material. It is designed to perform high thermal conductivity between high watt density chips like CPUs, GPUs, ASIC, Northbridge chipsets and heat sink. It demonstrates outstanding thermal performance and high reliability while wetting out the thermal interfaces under assembly pressure.



TYPICAL PROPERTIES

Properties		Thermal Grease 21-430SF	Test Method
Thermal	Thermal Conductivity (W/m·K)	3.0	ASTM D5470
	Thermal Resistance @40 psi (°C·cm^2/W)	0.153	ASTM D5470
	Operating Temperature Range(°C)	-40~125	JONES Test Method
Physical	Color	Grey	Visual
	Composition	Ceramic&Silicone-free	_ _
	Typical Minimum Bondline Thickness (μm)	25	JONES Test Method
	Viscosity @20rpm (Pa·s)	150	ASTM D2196
	Density (g/cm³)	2.3	ASTM D792
Electrical	Breakdown Voltage (KV AC /mm)	>12	ASTM D149
	Volume Resistivity (Ohm·cm)	10^12	ASTM D257
	Dielectric Constant @1MHz	4.8	ASTM D150
Regulatory	Flame Rating	V0	UL 94

Thermal Resistance





21 - 4 XX SF - YYY











- ① 21-Thermal management material
- 2 4-Thermal Grease
- ③ XX-Thermal Performance
- ④ SF-Silicon-free
- 4 YYYY-Package Size



ORDERING INFORMATION

Standard Package

Supplied in the package of 60ml syringe; Customizable packaging

Storage Requirement

0° to 35°C, 50%RH, sealing preservation 6 months from date of manufacture.

* Unopened Original Package

HANDLING PRECAUTIONS

FOR SAFE HANDLING INFORMATION OF THIS PRODUCT, PLEASE CONTACT WITH YOUR JONES REPRESENTATIVE FOR THE SAFETY DATA SHEET (SDS).

LIMITED WARRANTY INFORMATION

The information provided in this Technical Data Sheet including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the data of this TDS. Jones Corp is not, therefore, liable for the suitability of any Jones Corp products for any specific or general uses. Jones Corp shall not be liable for incidental or consequential damages of any kind.

FOR MORE INFORMATION

About our high performance materials, solutions and capabilities, please visit our website:

http://www.jones-corp.com

Disclaimer

- · The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the issuing date of this TDS. When using our products, no matter what type of equipment they might be used for, be sure to make a written agreement on the specifications with us in advance. The design and specifications in this TDS are subject to change without
- Do not use the products beyond the specifications described in this TDS. This TDS explains the typical performance of the products as individual component. Before use, check and evaluate their operations when installed in your products.
- The product provided in this TDS compliance with HSF.

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